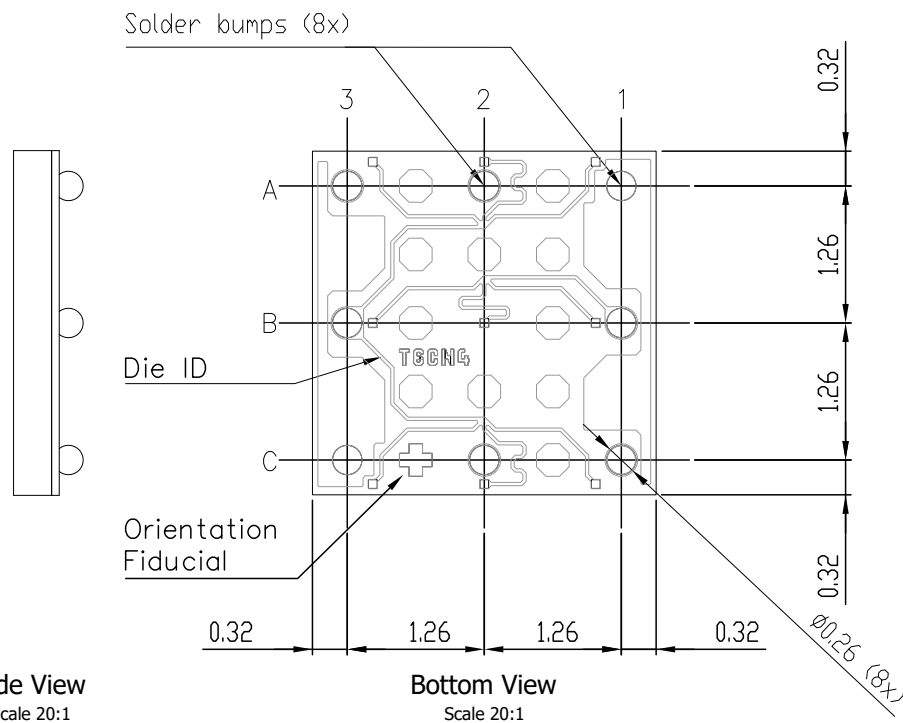
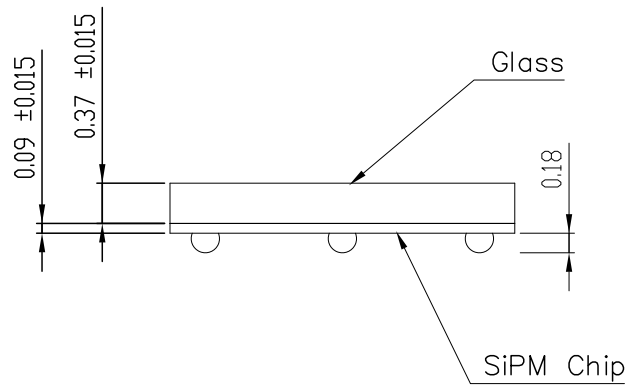


Top View
Scale 20:1



Side View
Scale 20:1

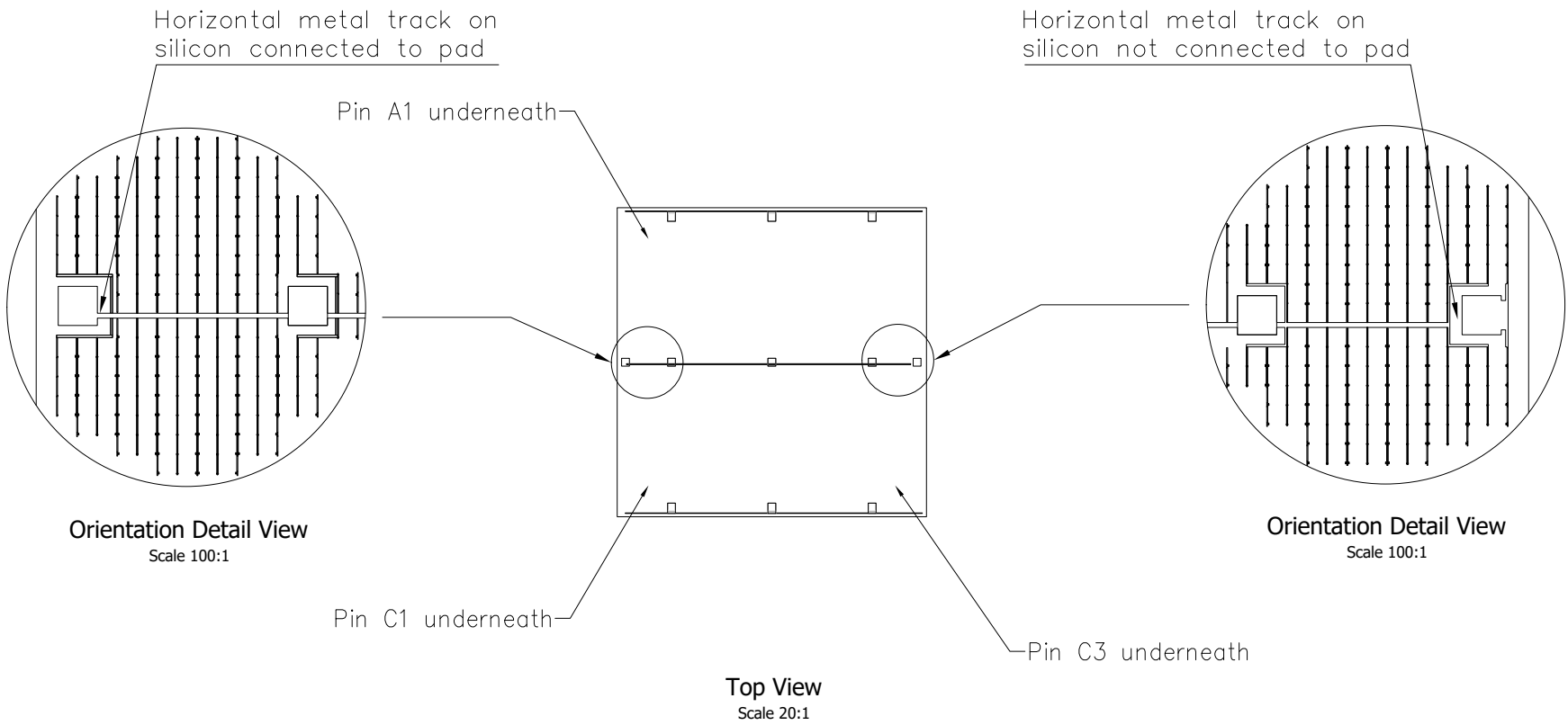
Bottom View
Scale 20:1



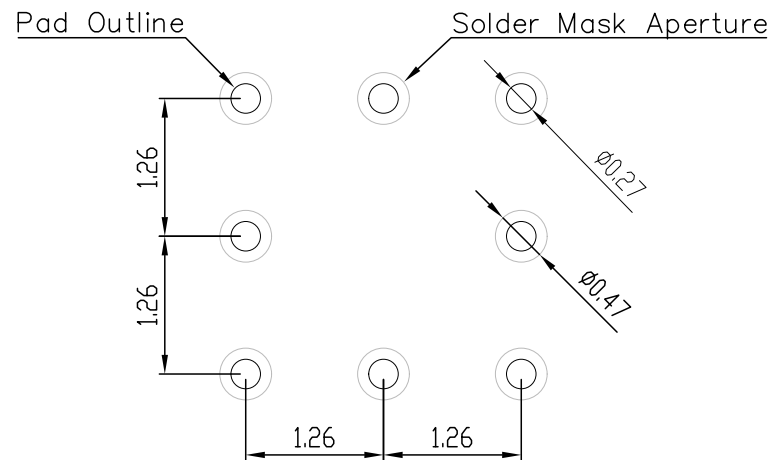
Side View
Scale 20:1

Pin Assignments	
Pin #	Function
A1	Cathode
A2	NC
A3	NC
B1	Anode
B3	Fast Output
C1	NC
C2	NC
C3	Cathode

DATE	26 June 2017	REVISION	B	SCALE:	20 : 1
SensL Technologies Ltd					Sheet
www.sensl.com					1 of 5
DWG. NO:	SND0186	DO NOT SCALE	ALL DIMENSIONS IN MM		
TITLE:					
MicroFJ-300XX-TSV-A2					
PROJECTION:					



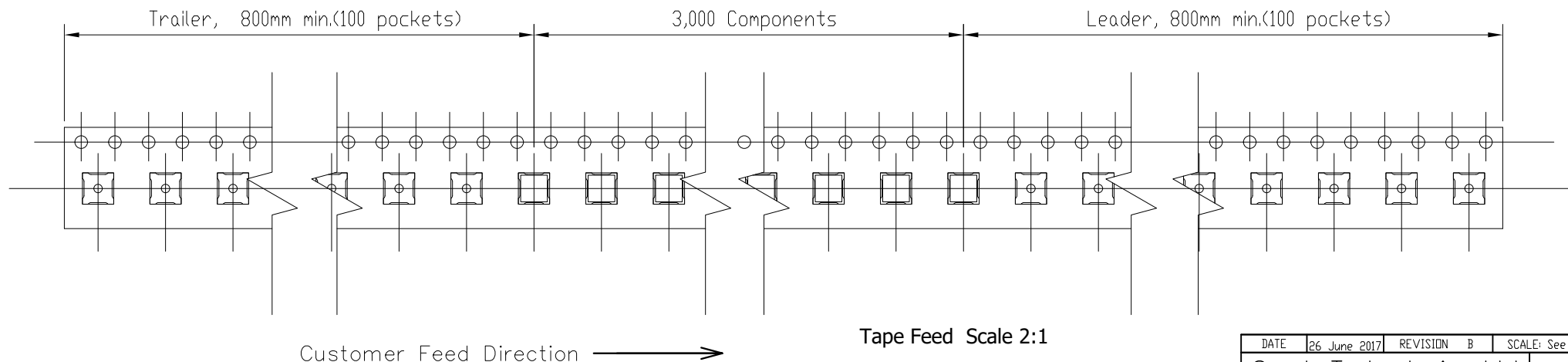
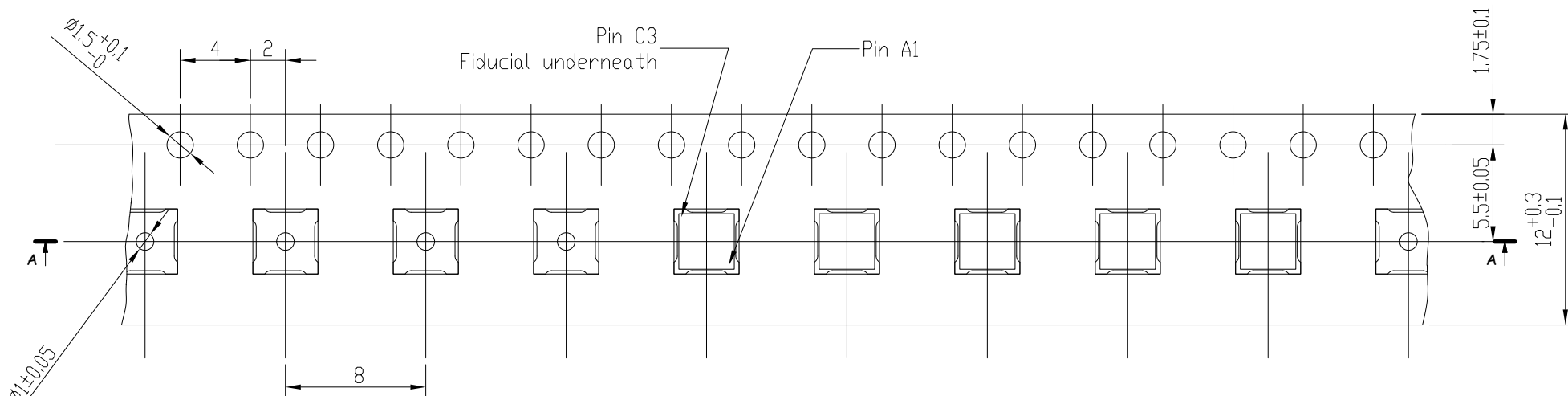
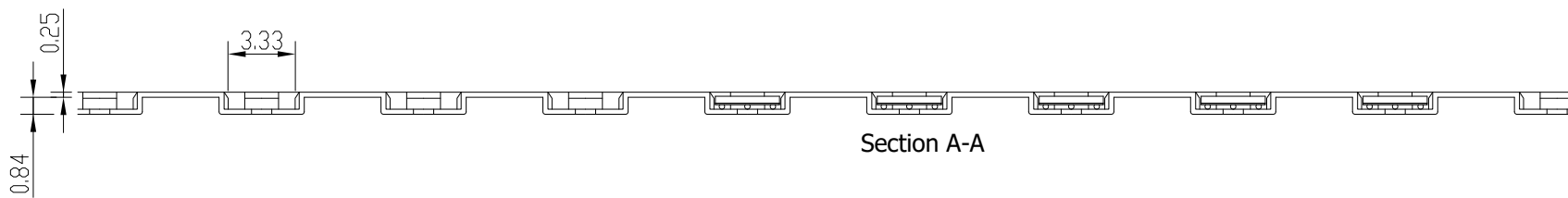
DATE	26 June 2017	REVISION	B	SCALE	20 : 1
SensL Technologies Ltd www.sensl.com					Sheet 2 of 5
DWG. NO:	SND0186	DO NOT SCALE	ALL DIMENSIONS IN MM		
TITLE: MicroFJ-300XX-TSV-A2					
PROJECTION:					



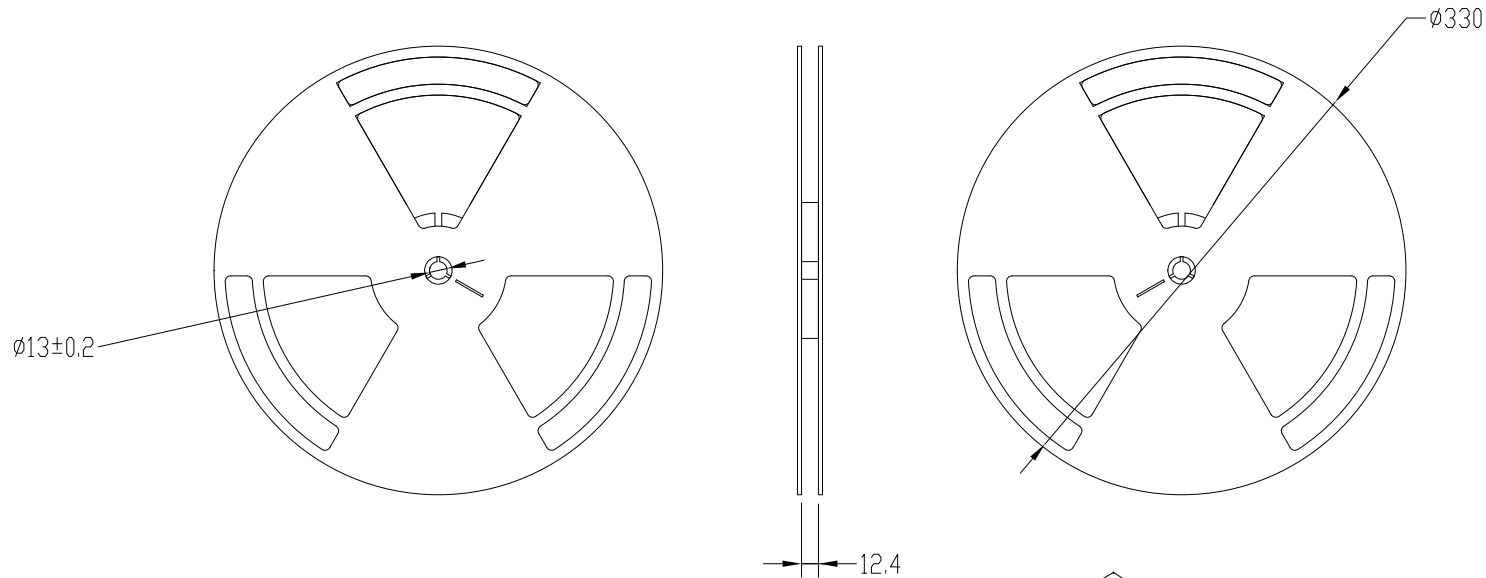
Recommended PCB Solder Footprint
Scale 20:1

NOTE: The No Connect (NC) pins are electrically isolated and should be soldered to a ground (or bias) plane to help with heat dissipation.

DATE	26 June 2017	REVISION	B	SCALE:	20 : 1
SensL Technologies Ltd					Sheet
www.sensl.com					3 of 5
DWG. NO:	SND0186	DO NOT SCALE	ALL DIMENSIONS IN MM		
TITLE:					
MicroFJ-300XX-TSV-A2					
PROJECTION:					

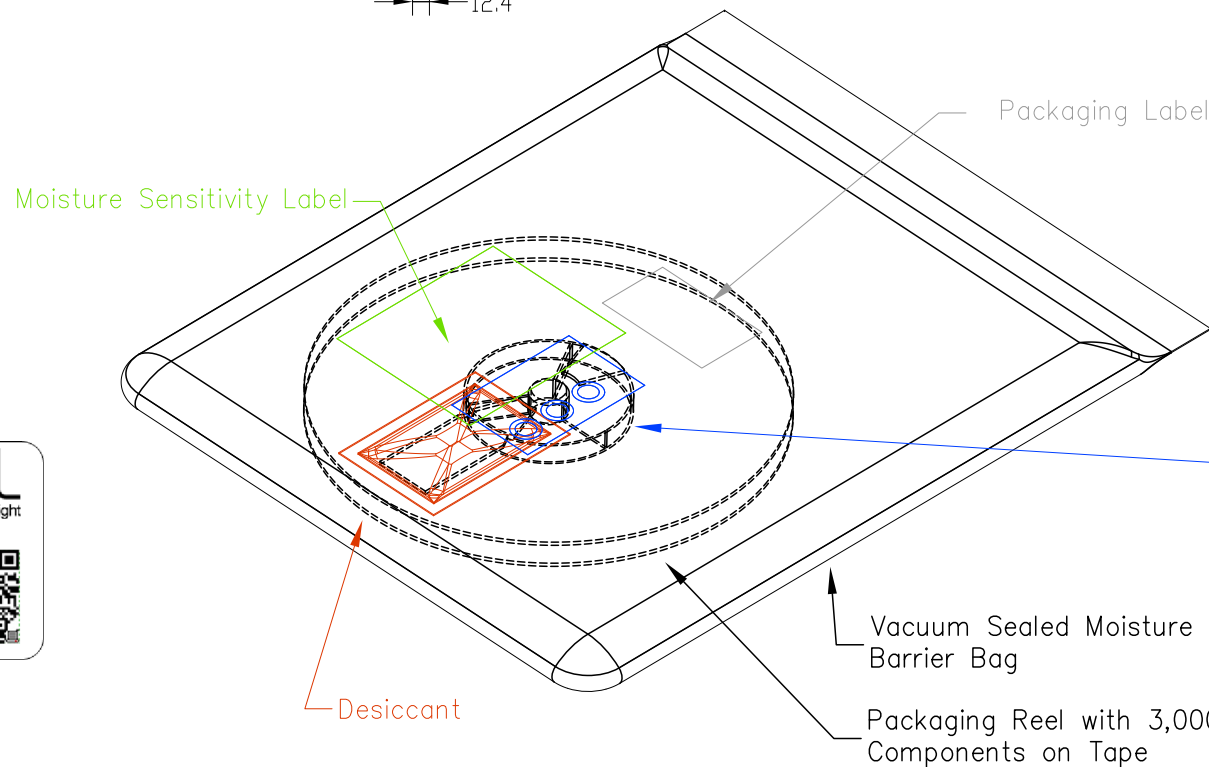


DATE	26 June 2017	REVISION	B	SCALE:	See Views
SensL Technologies Ltd					Sheet
www.sensl.com					4 of 5
DWG. NO:	SND0186	DO NOT SCALE	ALL DIMENSIONS IN MM		
TITLE:					
MicroFJ-300XX-TSV-A2					
PROJECTION:					



	CAUTION	3
MOISTURE SENSITIVE DEVICES		
1. Calculated shelf life in sealed bag: 24 months at $\le 40^{\circ}\text{C}$ and $\le 90\%$ relative humidity (RH)		
2. Peak package body temperature: <u>260</u> °C <small>If blank, see adjacent bar code label</small>		
3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must be:		
a) Mounted within: <u>168</u> hours of factory conditions $\le 30^{\circ}\text{C}$ 60% RH, or		
b) Stored per J-STD-033		
4. Devices require bake, before mounting, if: a) Humidity Indicator Card reads >10% for level 2a - 5a devices or >50% for level 2 devices when read at $25 \pm 5^{\circ}\text{C}$ b) 3a or 3b are not met.		
5. If baking is required, refer to IPC/JEDEC J-STD-033 for bake procedure.		
Bag Seal Date: <u>20 Mar. 2014</u> <small>If blank, see adjacent bar code label</small>		
<small>Note: Level and body temperature defined by IPC/JEDEC J-STD-020</small>		

Details of Moisture Sensitivity Label



5% LEVEL 2A - 5A PARTS Bake parts if 10% IS NOT BROWN and 5% IS AZURE	10% LEVEL 2 PARTS Bake parts if 60% IS NOT BROWN	60% LEVEL 2 PARTS IS NOT BROWN
BROWN-DRY AZURE-WET COBALT FREE HUMIDITY INDICATOR COMPLIES WITH IPC/JEDEC J-STD-033B		
<small>Initial Line: DO NOT put this card into a bag if 60% is AZURE!</small>		

Humidity Indicator Card

Humidity Indicator Card

sensl <small>sense light</small>
Part#: MicroFJ-300XX-TSV-A2
Revision: A2
Lot#: E4052
Quantity: 3000

Sample Packaging Label

DATE	26 June 2017	REVISION	B	SCALE	Not to scale
SensL Technologies Ltd www.sensl.com					Sheet 5 of 5
DWG. NO:	SND0186	DO NOT SCALE	ALL DIMENSIONS IN MM		
TITLE: MicroFJ-300XX-TSV-A2					
PROJECTION:		sensl <small>sense light</small>			